

What is claimed is:

1. A laminate for an HDD suspension comprising a stainless layer, polyimide resin layer, and conductive layer, wherein a thickness of the conductive layer is 10 μm or less.

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2. The laminate for an HDD suspension as described in claim 1, wherein the conductive layer is an alloyed copper foil having a strength of 500 MPa or more and an electric conductivity of 65 % or more.

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3. The laminate for an HDD suspension as described in claim 1 or 2, wherein a surface roughness (Ra) of the conductive layer is 0.15 μm or less.

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4. A production process of a laminate for an HDD suspension, wherein a laminate comprising a stainless layer, polyimide resin layer, and conductive layer is produced using the conductive layer having a thickness of larger than 10 μm , and thereafter only the conductive layer is subjected to chemical etching to thereby reduce a thickness of the conductive layer to 10 μm or less.

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5. The production process of a laminate for an HDD suspension as described in claim 4, wherein the conductive layer is an alloyed

copper foil having a strength of 500 MPa or more and an electric conductivity of 65 % or more.

6. The production process of a laminate for an HDD suspension
5 as described in claim 4, wherein the laminate after subjected to
chemical etching is subjected to supersonic treatment in an alkaline
solution.

7. The production process of a laminate for an HDD suspension
10 as described in claim 5, wherein the laminate after subjected to
chemical etching is subjected to supersonic treatment in an alkaline
solution.

8. The production process of a laminate for an HDD suspension
15 as described in any of claims 4 to 6, wherein the conductive layer
after subjected to chemical etching has a surface roughness (Ra)
of 0.15 μm or less.